

IN THE SPECIFICATION:

Paragraph beginning at line 3 of page 1 has been amended as follows:

The present invention relates to a sample manufacturing apparatus and, more specifically, to an apparatus for making test pieces for slice observation from a wafer with a transmission electron microscope (hereafter referred to as TEM) or a scanning electron microscope (hereafter referred to as SEM) utilizing ultra-fine processing using a focused ion beam (hereafter referred to as FIB).

Paragraph beginning at line 24 of page 3 has been amended as follows:

A manipulator, not shown, is used in taking out the TEM sample 107. A tip of a probe 108, made of a glass material, is brought close to a lateral slice 107a of the TEM sample 107. If the tip of the probe 108 is brought sufficiently close to the slice 107a, then as shown in Fig. 11C, the TEM sample 107 is attracted to the probe 108 due to static electricity. Then, with the TEM sample 107 still stuck to the tip, the probe 108 is moved onto a fixing table (not shown) that has been separately prepared, and the TEM sample 107 stuck to the tip is fixed to a specified part of the fixing table. In fixing the TEM sample 107 to the fixing

table at this time, it is possible to utilize deposition processing or static electricity. ~~Also,~~ depending Depending on the situation, it may also be possible to perform finishing processing for the TEM sample 107 fixed to the fixing table, table using the ion beam 100a.

Paragraph beginning at line 13 of page 8 has been amended as follows:

In the FIB sample manufacturing device disclosed in Japanese patent laid-open No. 2002-62226 ~~also~~, it is also

possible to solve the above described issue regarding operability, but there is the following type of problem.

Paragraph beginning at line 2 of page 9 has been amended as follows:

The object of the present invention is to solve each of the above described problems in the conventional art, and to provide a compact sample manufacturing device in which a sample stage and an observation sample holder (side entry stage) do not interfere.

Heading at line 14 of page 12 has been amended as follows:

DETAILED DESCRIPTION OF THE INVENTION PREFERRED EMBODIMENTS

Paragraph beginning at line 18 of page 12 has been amended as follows:

Fig. 1 is a schematic cross sectional drawing view showing of the schematic structure of an FIB device of a first embodiment of a sample manufacturing device of the present invention. This FIB device is for manufacturing a test piece such as a TEM sample or an SEM sample from a wafer, being an original sample, using a pick-up method, and is provided with a sample chamber 1 that is evacuated using an evacuation pump, not shown, with an FIB irradiation optical system 2, a side entry stage 3, a manipulator 4 and a sample stage 6 being provided in this sample chamber 1. Besides this, although not shown in Fig. 1, structures required for FIB processing, such as a gas gun and a secondary charged particle detector, are also provided in the sample chamber 1.

Paragraph beginning at line 20 of page 20 has been amended as follows:

With the FIB device of this embodiment, a test piece is manufactured by processing a specific site of the original sample 7 on the sample stage 6 using the second first FIB irradiation section, and this manufactured test piece is fixed to a tip of the observation sample holder 22 inserted from the side entry stage 3. Also, the test piece fixed to the tip of the observation sample holder 22 is subjected to final

finishing processing using the second FIB irradiation section. This test piece manufacture, fixing and finishing processing are similar to the case of the first embodiment described above.